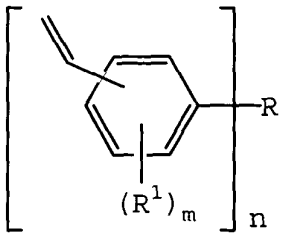
AMENDMENTS TO THE CLAIMS

1-8. (Cancelled)

9. (Currently Amended) The cured product according to claim [[8]] 14 wherein the dielectric loss tangent after curing is not more than 0.002.

10. (Original) A curable film which contains a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]



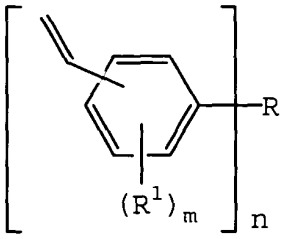
[1]

wherein R is a hydrocarbon skeleton which may have a substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and further contains a high polymer having film-forming ability.

11. (Original) The curable film according to claim 10 wherein a conductor layer has been formed on at least one surface of the curable film.

12. (Currently Amended) An electrical part having an insulator layer wherein the insulator layer contains a cured product of a low dielectric loss tangent resin

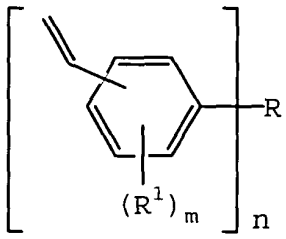
composition which contains a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]



[1]

wherein R is a hydrocarbon skeleton which may have a substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and further contains at least one member selected from a high ~~plolymer~~ polymer having a weight average molecular weight of not less than 5,000 and a filler.

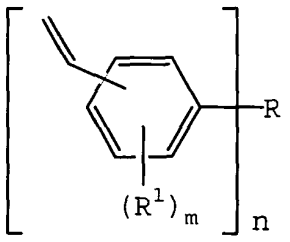
13. (Original) A method for producing an electrical part having an insulator layer wherein the insulator layer is a curable film containing a low dielectric loss tangent resin composition which contains a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]



[1]

wherein R is a hydrocarbon skeleton which may have a substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and further contains a high polymer having film-forming ability, and the curable film is lamination-bonded onto a conductor layer.

14. (New) A cured product obtained by curing a low dielectric loss tangent resin composition, wherein said low dielectric loss tangent resin composition contains a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]



[1]

wherein R is a hydrocarbon skeleton which may have a substituent, R^1 is hydrogen, methyl or ethyl, m is an integer of 1-4 and n is an integer of 2 or more, and wherein said low dielectric loss tangent resin composition further contains at least one member selected from a high polymer having a weight average molecular weight of not less than 5,000 and a filler.